

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	10/624601.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L2	441	(imperfect adj connection) or (discontinued adj areas)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L3	1	L1 and L2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L4	259	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L5	11	takenaka-yuuichi.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L6	6051819	gap or hole or (imperfect near connection) or space	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L7	598671	(insulat\$3 near3 (substrate or layer or part))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L8	280146	L7 and L6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

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L9	89	L8 and L4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L10	438531	resin and conduct\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L11	26	L9 and L10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L12	194444	thermal near (expansion or expanding or expand)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L13	8	L12 and L4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L14	2	L11 and L12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L15	1539	349/158.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L16	280	L15 and L7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L17	1406	349/155.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

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L18	326	L17 and L7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L19	7	L2 and "349".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L20	54402	insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L21	1	L1 and L7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L22	6051819	gap or hole or (imperfect near connection) or space	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L23	598671	(insulat\$3 near3 (substrate or layer or part))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L24	280146	L22 and L23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L25	6277529	gap or hole or (imperfect near connection) or space or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L26	283967	L25 and L23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

EAST Search History

L27	1539	349/158.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L28	197	L26 and L27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L29	267483	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L30	19937	L29 and L25 and L23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L31	965	349/84.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L32	1	L30 and L31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L33	1406	349/155.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L34	12	L30 and L33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L35	965	349/84.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

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L36	259	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L37	1406	349/155.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L38	1539	349/158.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L39	1165	349/138.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L40	6051819	gap or hole or (imperfect near connection) or space	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L41	632	L39 and L40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L42	267483	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L43	61416	L40 same L42	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L44	10	L43 and L39	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

EAST Search History

L45	378	349/142.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L46	354	349/150.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L47	2	L43 and L45	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L48	57	L43 and L46	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L49	295	349/151.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L50	164068	resin same (conductive or conductor or conducting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L51	267483	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L52	5394	L50 same L51	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L53	39348	"349".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

EAST Search History

L54	53	L52 and L53	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L55	7049936	gap or hole or (imperfect near connection) or space or slot or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L56	6060	(multi-layered or (multi adj layered) or (multiple adj layered) or multi-layer or (multi adj layer) or (multiple adj layer)) with L51	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L57	1791	L55 same L56	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L58	11	L53 and L57	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L59	141279	L51 and L55	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L60	1156	L59 and L53	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L61	121	L60 and L50	USPAT	OR	ON	2006/05/25 17:53
L62	379563	Sharp Kabushiki Kaisha.As.	USPAT	OR	ON	2006/05/25 17:53
L63	54533	L62 and slot	USPAT	OR	ON	2006/05/25 17:53
L64	82	L62 and L57	USPAT	OR	ON	2006/05/25 17:53
L65	2	L64 and "349".clas.	USPAT	OR	ON	2006/05/25 17:53
L66	82234	thermal adj expans\$	USPAT	OR	ON	2006/05/25 17:53
L67	15028	"349".clas.	USPAT	OR	ON	2006/05/25 17:53
L68	573	L66 and L67	USPAT	OR	ON	2006/05/25 17:53
L69	492	L68 and L55	USPAT	OR	ON	2006/05/25 17:53

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L70	147	L66 and L50 and L56 and L55	USPAT	OR	ON	2006/05/25 17:53
L71	7	("4506004" "4715117" "4728568" "5591353" "6272745" "6276055" "6631838").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L72	267483	PCB or (printed adj circuit adj board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L73	164068	resin same (conductive or conductor or conducting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L74	7049936	gap or hole or (imperfect near connection) or space or slot or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L75	6060	(multi-layered or (multi adj layered) or (multiple adj layered) or multi-layer or (multi adj layer) or (multiple adj layer)) with L72	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L76	82234	thermal adj expan\$5	USPAT	OR	ON	2006/05/25 17:53
L77	147	L76 and L73 and L75 and L74	USPAT	OR	ON	2006/05/25 17:53
L78	24293	TCP or (tape adj carrier adj package) or T-C-P	USPAT	OR	ON	2006/05/25 17:53
L79	5	L73 and L75 and L74 and L76 and L78	USPAT	OR	ON	2006/05/25 17:53
L80	259	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L81	8	L80 and L76	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L82	9	L73 and L75 and L74 and L78	USPAT	OR	ON	2006/05/25 17:53
L83	295	349/151.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

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L84	449	349/152.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L85	5997723	hannstar display corp.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L86	24	L85 and L77	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L87	1	09/204130.app.	USPAT	OR	ON	2006/05/25 17:53
L88	59	("3913219" "3947956" "4416914" "4555745" "4566186" "4632845" "4774634" "4808434" "4870746" "5225969" "5298687" "5305523" "5347258" "5354599" "5384434" "5428190" "5502889" "5527998" "5599595" "5688584" "5716663" "5727310" "5747222" "5758575" "5763058" "5814366").PN. OR ("6021050").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L89	3085	428/209.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L90	19	L89 and L77	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L91	1076	428/194.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L92	3875281	L74	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L93	513	L74 and L91	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L94	2	09/136201.app.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L95	4	L77 and "349".clas.	USPAT	OR	ON	2006/05/25 17:53
L96	70	L78 and (prevent\$3 with L76)	USPAT	OR	ON	2006/05/25 17:53

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L97	3446	438/106.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L98	65	L97 and L75 and L74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L99	86	multiplelayer or multiplelayering with L72	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L100	48	L99 and L74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L101	14483	prevent\$3 same L76	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L102	11629	L101 and L74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L103	74	L102 and L75	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L104	11629	L101 and L74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L105	4729785	(imperfect near connection) or space or slot or slit	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53

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L106	2781	L75 and L105	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L107	525	L106 and L73	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L108	598671	(insulat\$3 near3 (substrate or layer or part))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L109	132	L108 and L78 and L76	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L110	259	345/206.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L111	1	"6738123".pn. and insulat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L112	4	("6738123").URPN.	USPAT	OR	ON	2006/05/25 17:53
L113	6	("5745202" "5969780" "6198051" "6198521" "6369867" "6573954").PN. OR ("6870589").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/25 17:53
L114	54402	insulating adj substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L115	7	L114 and L78 and L75 and L74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L116	19	("6121553").URPN.	USPAT	OR	ON	2006/05/25 17:53

EAST Search History

L117	1	L115 and (semiconductor adj chip)	USPAT	OR	ON	2006/05/25 17:53
L118	0	10/624601.app.	USPAT	OR	ON	2006/05/25 17:53
L119	1	10/624601.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L120	1	L119 and (semiconductor adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L121	1	resin and 09/204130.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 17:53
L122	28	((((imperfect or irregular) near part) or gap or hole or space) same (MLPCB or (Multi-layer\$2 near PCB) or (multi\$3 near layer\$2 near printed near circuit near board))) same insulat\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:24
L123	0	L122 and 361/721.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:20
L124	0	((((imperfect or irregular) near part) or gap or hole or space) same (MLPCB or (Multi-layer\$2 near PCB) or (multi\$3 near layer\$2 near printed near circuit near board))))).clm. and 361/721.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:27
L125	56	((((imperfect or irregular) near part) or gap or hole or space)).clm. and 361/721.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:27
L126	78	((((imperfect or irregular) near part) or gap or hole or space)).clm. and 349/150.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:22
L127	44	((((imperfect or irregular) near part) or gap or hole or space)).clm. and 345/206.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:23

EAST Search History

L128	76	(((((imperfect or irregular) near part) or gap or hole or space))).clm. and 349/151.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:23
L129	547	(((((imperfect or irregular) near part) or gap or hole or space))).clm. and 428/209.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:23
L130	92	(((((imperfect or irregular) near part) or gap or hole or space))).clm. and 428/194.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:23
L131	79	((MLPCB or (Multi-layer\$2 near PCB) or (multi\$3 near layer\$2 near printed near circuit near board))) same insulat\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:25
L132	445	((MLPCB or (Multi-layer\$2 near PCB) or (multi\$3 near layer\$2 near printed near circuit near board))).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:25
L133	1	(L125 or L126 or L127 or L128 or L129 or L130) and L132	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:26
L134	5	(((((imperfect or irregular) near part) or gap or hole or space))).clm. and 361/78.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/05/25 18:27